



BT139B-800G

4Q Triac

27 September 2013

Product data sheet

1. General description

Planar passivated four quadrant triac in a SOT404 (D2PAK) surface-mountable plastic package intended for use in applications requiring high bidirectional transient and blocking voltage capability and high thermal cycling performance. Typical applications include motor control, industrial and domestic lighting, heating and static switching.

2. Features and benefits

- High blocking voltage capability
- Least sensitive gate for highest noise immunity
- Planar passivated for voltage ruggedness and reliability
- Surface-mountable package
- Triggering in all four quadrants

3. Applications

- General purpose motor control
- General purpose switching

4. Quick reference data

Table 1. Quick reference data

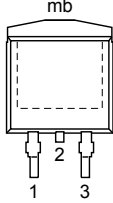
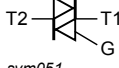
| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------------|--------------------------------------|---|-----|-----|-----|------|
| V_{DRM} | repetitive peak off-state voltage | | - | - | 800 | V |
| I_{TSM} | non-repetitive peak on-state current | full sine wave; $T_{\text{J}(\text{init})} = 25\text{ }^{\circ}\text{C}$; $t_{\text{p}} = 20\text{ ms}$; Fig. 4 ; Fig. 5 | - | - | 155 | A |
| $I_{\text{T(RMS)}}$ | RMS on-state current | full sine wave; $T_{\text{mb}} \leq 99\text{ }^{\circ}\text{C}$; Fig. 1 ; Fig. 2 ; Fig. 3 | - | - | 16 | A |
| Static characteristics | | | | | | |
| I_{GT} | gate trigger current | $V_{\text{D}} = 12\text{ V}$; $I_{\text{T}} = 0.1\text{ A}$; T2+ G+; $T_{\text{J}} = 25\text{ }^{\circ}\text{C}$; Fig. 7 | - | 5 | 50 | mA |
| | | $V_{\text{D}} = 12\text{ V}$; $I_{\text{T}} = 0.1\text{ A}$; T2+ G-; $T_{\text{J}} = 25\text{ }^{\circ}\text{C}$; Fig. 7 | - | 8 | 50 | mA |
| | | $V_{\text{D}} = 12\text{ V}$; $I_{\text{T}} = 0.1\text{ A}$; T2- G-; $T_{\text{J}} = 25\text{ }^{\circ}\text{C}$; Fig. 7 | - | 10 | 50 | mA |



| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------|-----------|---|-----|-----|-----|------|
| | | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2- G+; $T_j = 25\text{ °C}$; Fig. 7 | - | 22 | 100 | mA |

5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|--------------------------------|--|--|
| 1 | T1 | main terminal 1 |  <p style="text-align: center;">D2PAK (SOT404)</p> |  <p style="text-align: center;"><i>sym051</i></p> |
| 2 | T2 | main terminal 2 | | |
| 3 | G | gate | | |
| mb | T2 | mounting base; main terminal 2 | | |

6. Ordering information

Table 3. Ordering information

| Type number | Package | | |
|-------------|---------|--|---------|
| | Name | Description | Version |
| BT139B-800G | D2PAK | plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped) | SOT404 |

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|--------------|--------------------------------------|---|-----|-----|-------------|
| V_{DRM} | repetitive peak off-state voltage | | - | 800 | V |
| $I_{T(RMS)}$ | RMS on-state current | full sine wave; $T_{mb} \leq 99\text{ °C}$; Fig. 1 ; Fig. 2 ; Fig. 3 | - | 16 | A |
| I_{TSM} | non-repetitive peak on-state current | full sine wave; $T_{j(init)} = 25\text{ °C}$; $t_p = 20\text{ ms}$; Fig. 4 ; Fig. 5 | - | 155 | A |
| | | full sine wave; $T_{j(init)} = 25\text{ °C}$; $t_p = 16.7\text{ ms}$ | - | 170 | A |
| I^2t | I^2t for fusing | $t_p = 10\text{ ms}$; SIN | - | 120 | A^2s |
| di_T/dt | rate of rise of on-state current | $I_T = 20\text{ A}$; $I_G = 0.2\text{ A}$; $dI_G/dt = 0.2\text{ A}/\mu s$; T2+ G+ | - | 50 | $A/\mu s$ |
| | | $I_T = 20\text{ A}$; $I_G = 0.2\text{ A}$; $dI_G/dt = 0.2\text{ A}/\mu s$; T2+ G- | - | 50 | $A/\mu s$ |
| | | $I_T = 20\text{ A}$; $I_G = 0.2\text{ A}$; $dI_G/dt = 0.2\text{ A}/\mu s$; T2- G- | - | 50 | $A/\mu s$ |
| | | $I_T = 20\text{ A}$; $I_G = 0.2\text{ A}$; $dI_G/dt = 0.2\text{ A}/\mu s$; T2- G+ | - | 10 | $A/\mu s$ |
| I_{GM} | peak gate current | | - | 2 | A |
| P_{GM} | peak gate power | | - | 5 | W |
| $P_{G(AV)}$ | average gate power | over any 20 ms period | - | 0.5 | W |
| T_{stg} | storage temperature | | -40 | 150 | $^{\circ}C$ |
| T_j | junction temperature | | - | 125 | $^{\circ}C$ |

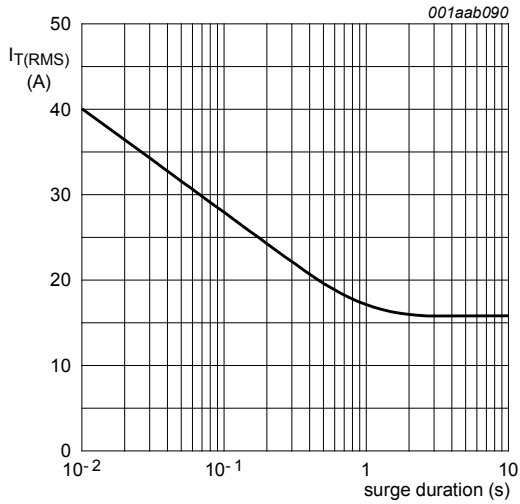


Fig. 1. RMS on-state current as a function of surge duration; maximum values

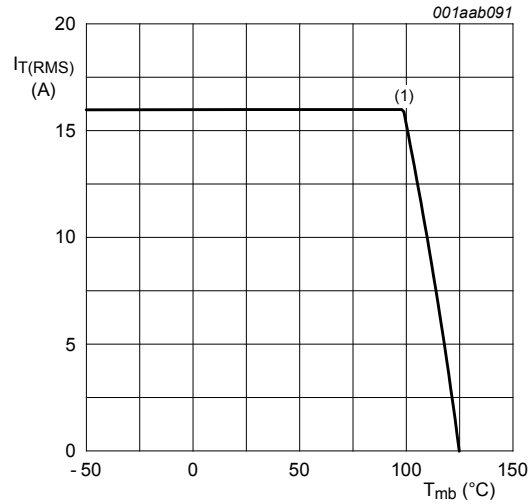


Fig. 2. RMS on-state current as a function of mounting base temperature; maximum values

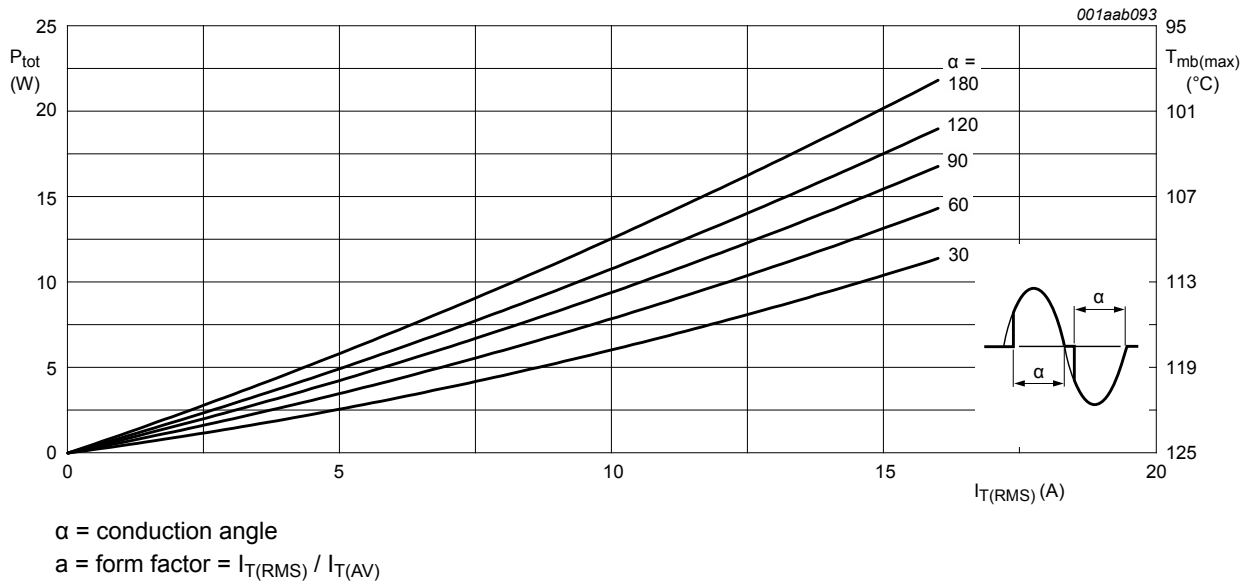
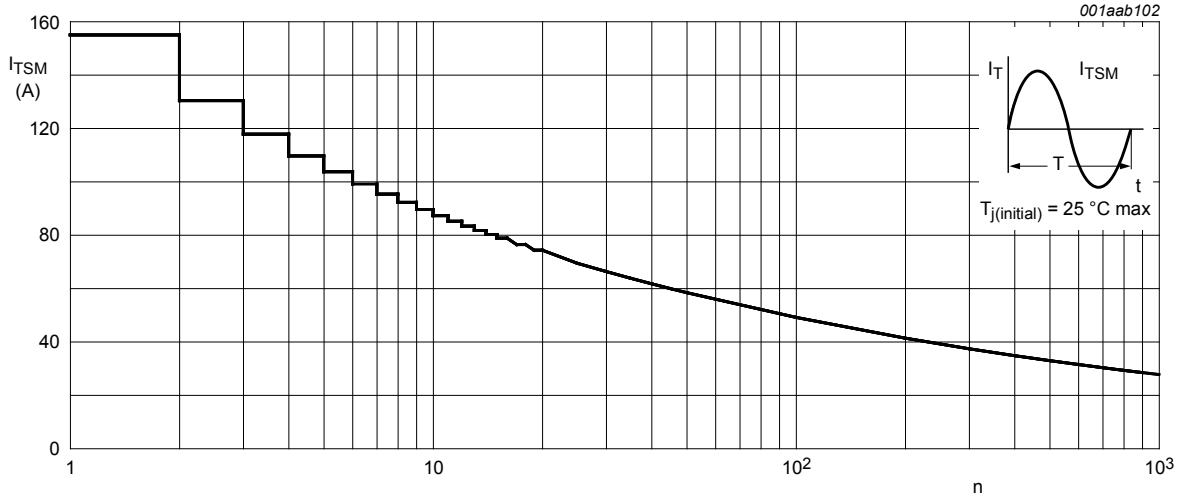
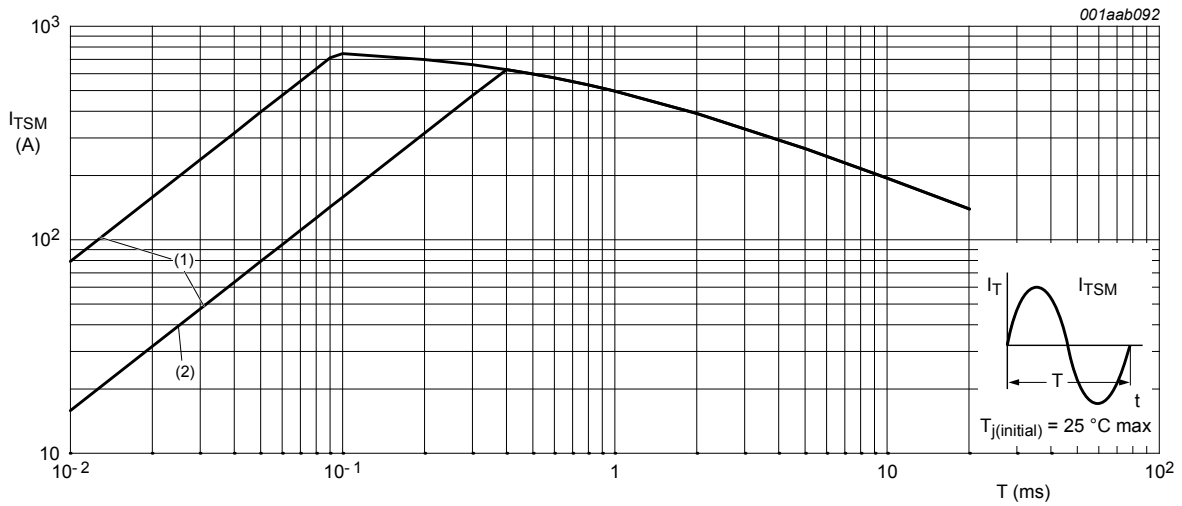


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values.



$f = 50\text{ Hz}$; $n = \text{number of cycles}$

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



$t_p \leq 20\text{ ms}$

(1) dI_T/dt limit

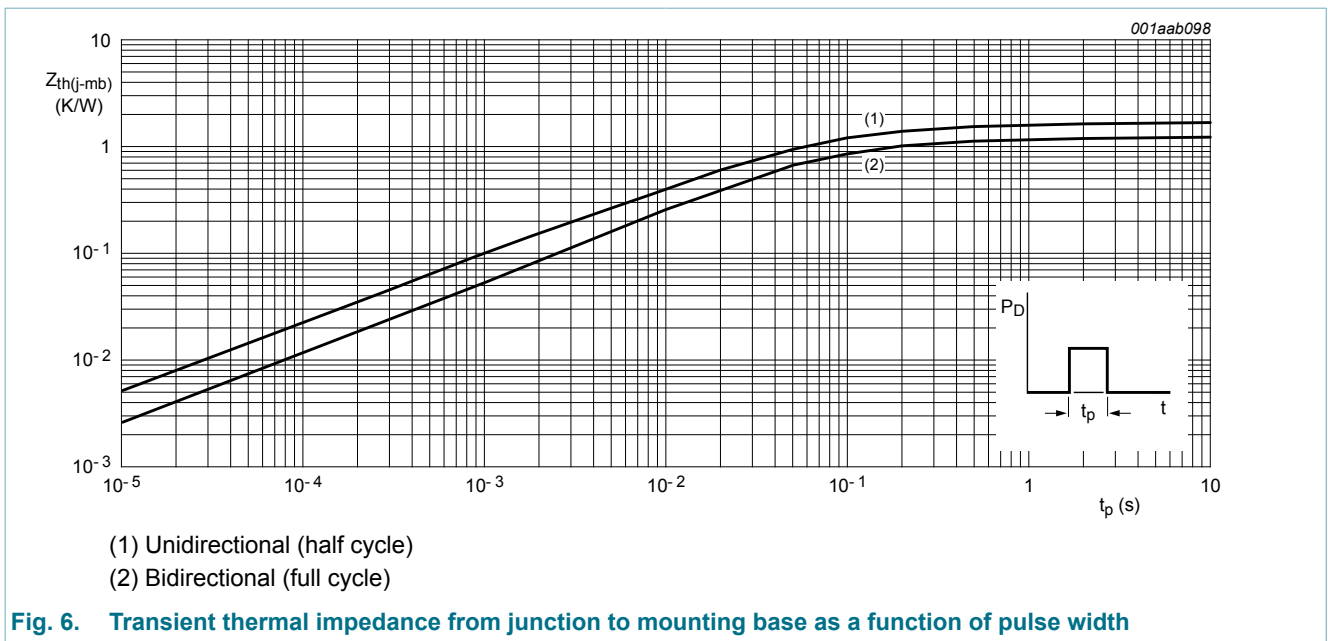
(2) T2- G+ quadrant limit

Fig. 5. Non-repetitive peak on-state current as a function of pulse width; maximum values

8. Thermal characteristics

Table 5. Thermal characteristics

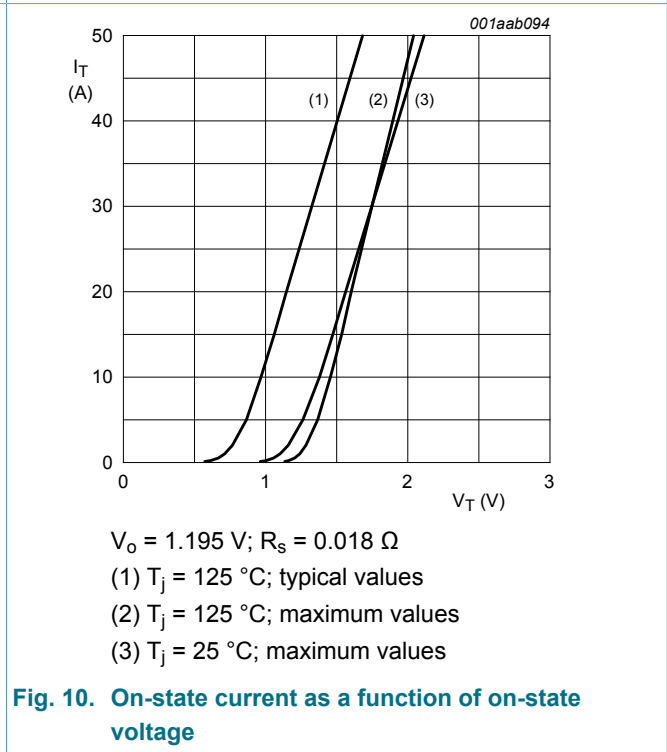
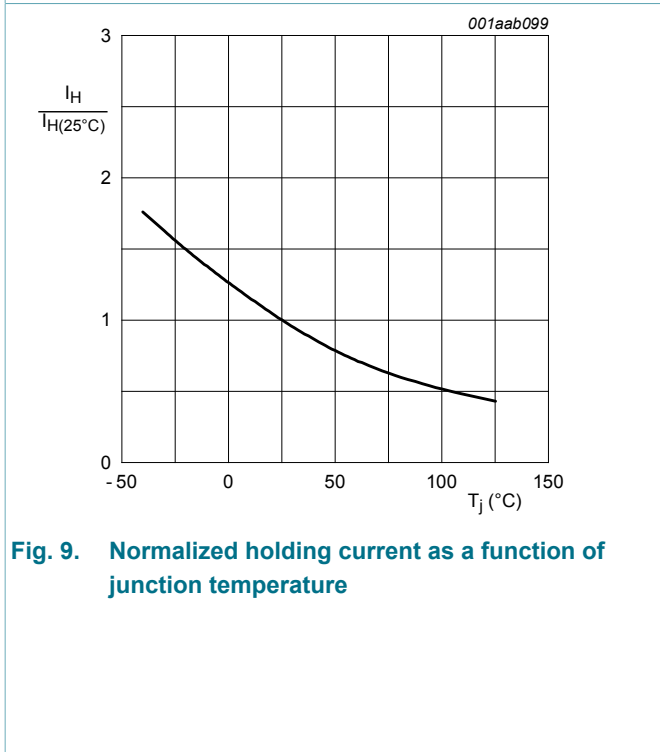
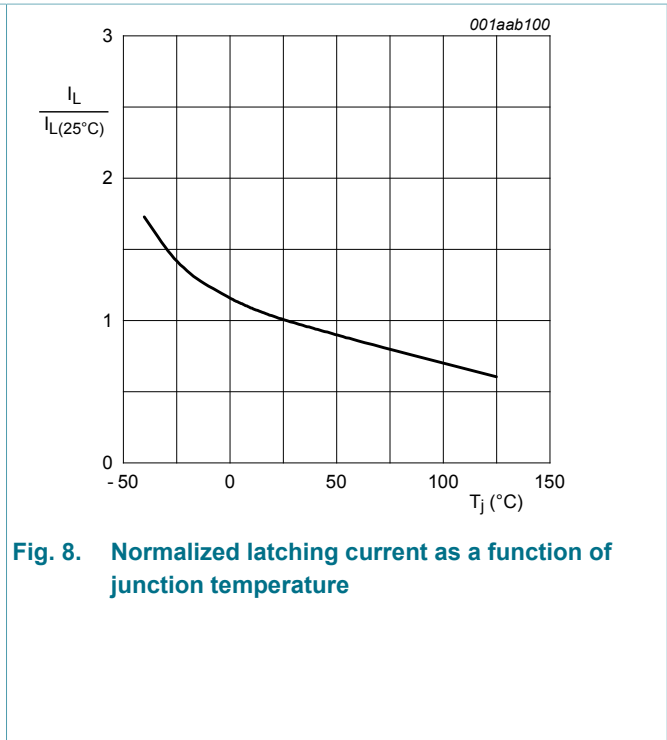
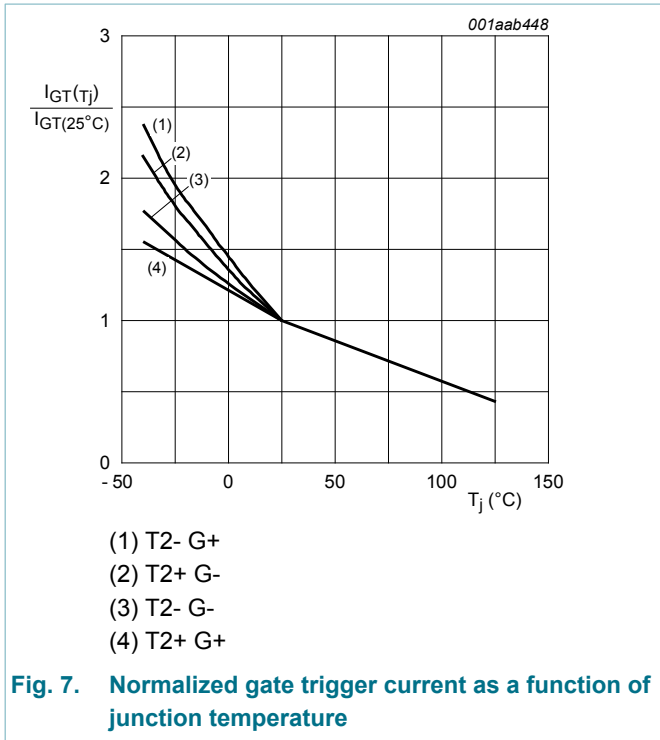
| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------|---|------------------------------|-----|-----|-----|------|
| $R_{th(j-mb)}$ | thermal resistance from junction to mounting base | half cycle; Fig. 6 | - | - | 1.7 | K/W |
| | | full cycle; Fig. 6 | - | - | 1.2 | K/W |
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | minimum footprint; FR4 board | - | 55 | - | K/W |

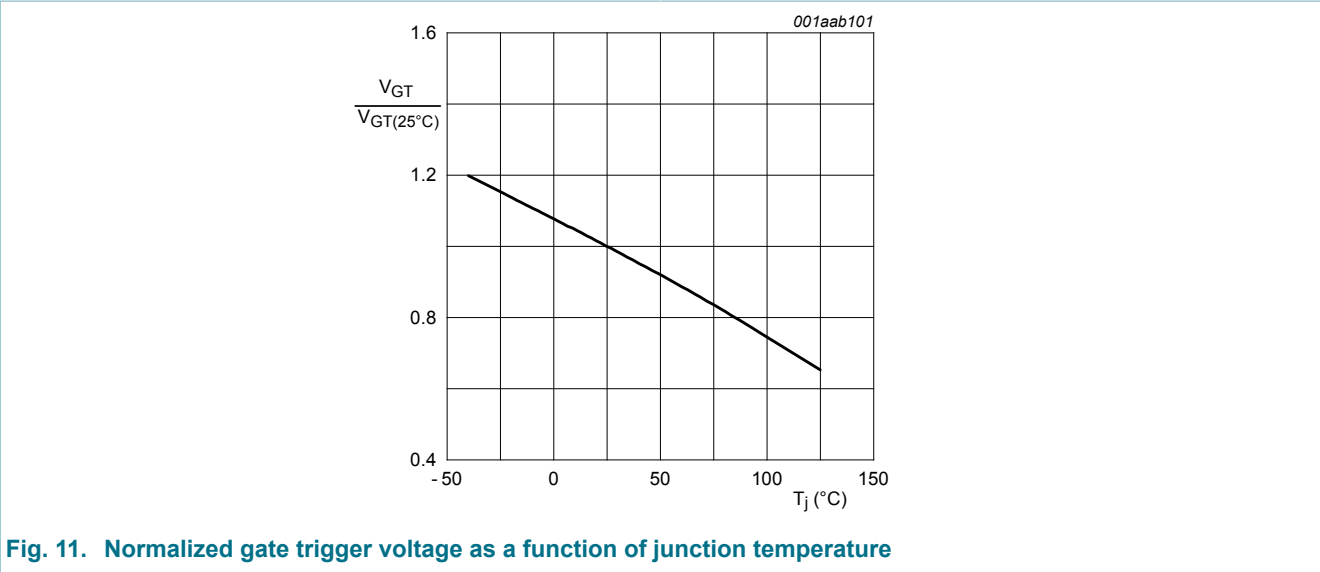


9. Characteristics

Table 6. Characteristics

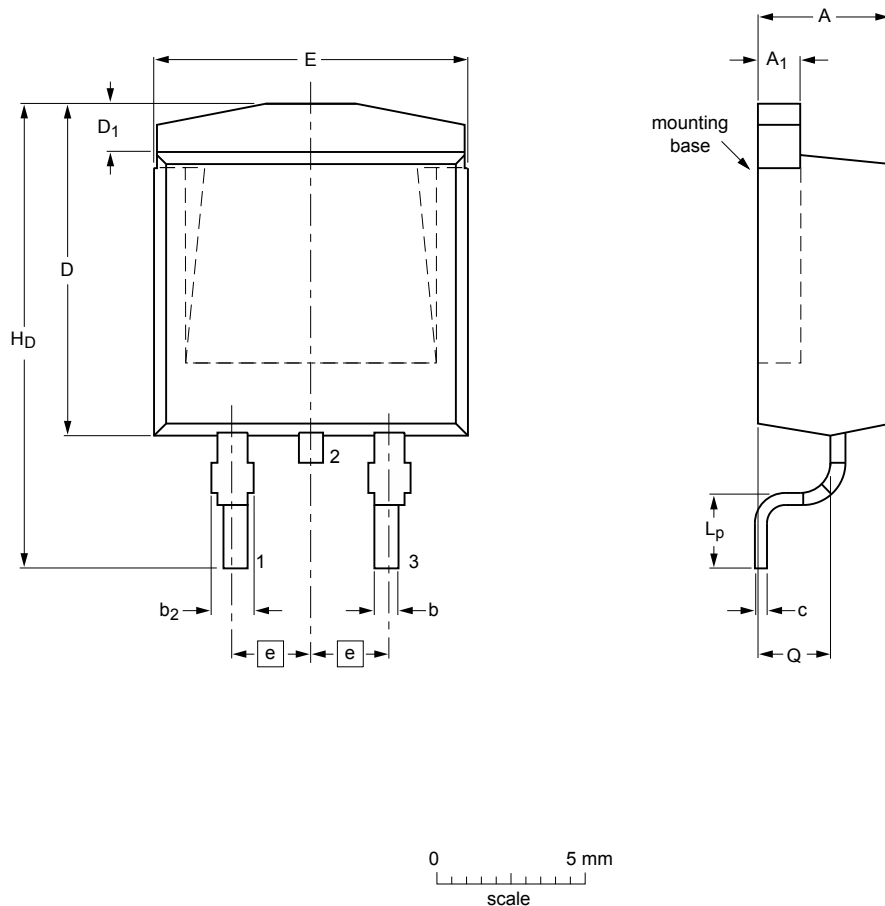
| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------------------|---------------------------------------|---|------|-----|-----|------|
| Static characteristics | | | | | | |
| I _{GT} | gate trigger current | V _D = 12 V; I _T = 0.1 A; T2+ G+; T _j = 25 °C; Fig. 7 | - | 5 | 50 | mA |
| | | V _D = 12 V; I _T = 0.1 A; T2+ G-; T _j = 25 °C; Fig. 7 | - | 8 | 50 | mA |
| | | V _D = 12 V; I _T = 0.1 A; T2- G-; T _j = 25 °C; Fig. 7 | - | 10 | 50 | mA |
| | | V _D = 12 V; I _T = 0.1 A; T2- G+; T _j = 25 °C; Fig. 7 | - | 22 | 100 | mA |
| I _L | latching current | V _D = 12 V; I _G = 0.1 A; T2+ G+; T _j = 25 °C; Fig. 8 | - | 7 | 60 | mA |
| | | V _D = 12 V; I _G = 0.1 A; T2+ G-; T _j = 25 °C; Fig. 8 | - | 20 | 90 | mA |
| | | V _D = 12 V; I _G = 0.1 A; T2- G-; T _j = 25 °C; Fig. 8 | - | 8 | 60 | mA |
| | | V _D = 12 V; I _G = 0.1 A; T2- G+; T _j = 25 °C; Fig. 8 | - | 10 | 90 | mA |
| I _H | holding current | V _D = 12 V; T _j = 25 °C; Fig. 9 | - | 6 | 60 | mA |
| V _T | on-state voltage | I _T = 20 A; T _j = 25 °C; Fig. 10 | - | 1.2 | 1.6 | V |
| V _{GT} | gate trigger voltage | V _D = 12 V; I _T = 0.1 A; T _j = 25 °C; Fig. 11 | - | 0.7 | 1 | V |
| | | V _D = 400 V; I _T = 0.1 A; T _j = 125 °C; Fig. 11 | 0.25 | 0.4 | - | V |
| I _D | off-state current | V _D = 800 V; T _j = 125 °C | - | 0.1 | 0.5 | mA |
| Dynamic characteristics | | | | | | |
| dV _D /dt | rate of rise of off-state voltage | V _{DM} = 536 V; T _j = 125 °C; (V _{DM} = 67% of V _{DRM}); exponential waveform; gate open circuit | 200 | 250 | - | V/μs |
| dV _{com} /dt | rate of change of commutating voltage | V _D = 400 V; T _j = 95 °C; dI _{com} /dt = 7.2 A/ms; I _T = 16 A; gate open circuit | 10 | 20 | - | V/μs |
| t _{gt} | gate-controlled turn-on time | I _{TM} = 20 A; V _D = 800 V; I _G = 0.1 A; dI _G /dt = 5 A/μs | - | 2 | - | μs |





10. Package outline

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped) SOT404



Dimensions (mm are the original dimensions)

| Unit | A | A ₁ | b | b ₂ | c | D | D ₁ | E | e | H _D | L _p | Q |
|------|-----|----------------|------|----------------|------|----|----------------|------|------|----------------|----------------|-----|
| max | 4.5 | 1.40 | 0.85 | 1.45 | 0.64 | 11 | 1.6 | 10.3 | | 15.8 | 2.9 | 2.6 |
| nom | | | | | | | | | 2.54 | | | |
| min | 4.1 | 1.27 | 0.60 | 1.05 | 0.46 | | 1.2 | 9.7 | | 14.8 | 2.1 | 2.2 |

sot404_po

| Outline version | References | | | European projection | Issue date |
|-----------------|------------|-------|-------|---------------------|------------------------|
| | IEC | JEDEC | JEITA | | |
| SOT404 | | | | | -06-03-16- 13-02-25 |

Fig. 12. Package outline D2PAK (SOT404)

11. Soldering

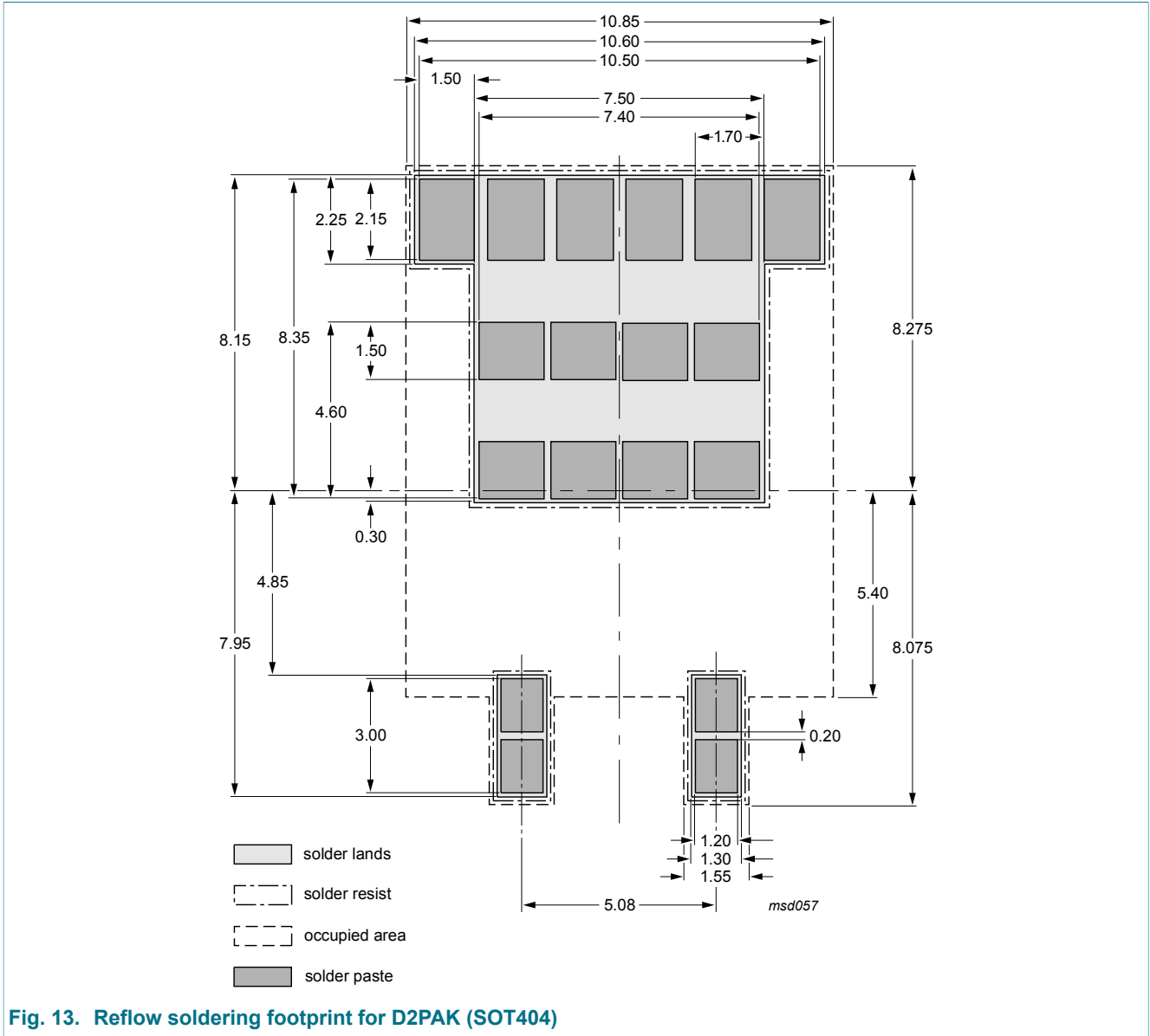


Fig. 13. Reflow soldering footprint for D2PAK (SOT404)

12. Legal information

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| Document status [1][2] | Product status [3] | Definition |
|--------------------------------|--------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

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- [2] The term 'short data sheet' is explained in section "Definitions".
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